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DIE MOVING PIERCING DEVICE

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Abstract

PURPOSE: To lightly move a die and to reduce the die cost by pressurizing an upper die, punching by a punch and die with a die set floating device via a preceding pressing pin and providing the means to move the die set in rail direction by a driving device.

CONSTITUTION: When a ram 1 is descended by feeding a work on a die, it pushes down an upper die 6 with compressing an urethane material, etc. 11. A preceding pressing pin 13 pushes down a rail holder 22 by abutting it to seat a lower die 7 on the supporting face 27 of the lower die base 4 by descending a die set floating device 3. With further descent of the upper die 6, a punch 8 makes a hole on a work by fitting into a die hole 14. With the actuation of a driving device 5, the die set 2 including the lower die 7 is moved with a linear bearing 23 on a rail 22 by the ascent of the die floating device 3. A die cost can thus be reduced and the movement of dies can lightly be performed.
